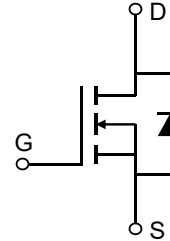


Description

Features

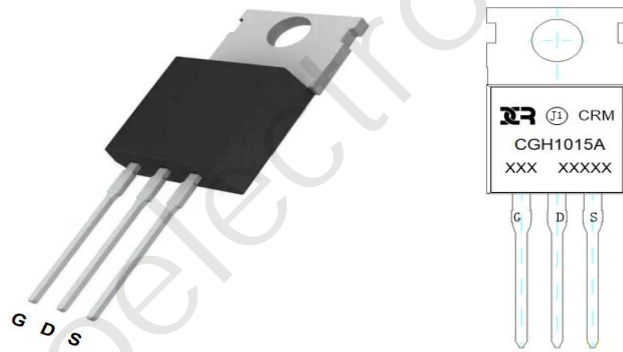
- 100V, 40A
 $R_{DS(ON)}$ Typ = 16mΩ @ $V_{GS} = 10V$
 Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	TUBE(pcs)	Inner Box (pcs)	Per Carton (pcs)
CRMCGH1015A	CRMCGH1015A	TO-220C-3L	TUBE	50	2000	8000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units	
V _{DS}	Drain-to-Source Voltage	100	V	
V _{GS}	Gate-to-Source Voltage	±20	V	
I _D	Continuous Drain Current	T _C = 25°C	40	A
		T _C = 100°C	24	A
I _{DM}	Pulsed Drain Current ⁽¹⁾	160	A	
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾	64	mJ	
P _D	Power Dissipation	T _C = 25°C	56.8	W
R _{θJC}	Thermal Resistance, Junction to Case	2.2	°C/W	
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C	

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.4	3	3.6	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 20A	-	16	20.8	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 50V, f = 1MHz	-	668	-	pF
C _{oss}	Output Capacitance		-	271	-	pF
C _{rss}	Reverse Transfer Capacitance		-	8	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 50V, I _D = 5A	-	11	-	nC
Q _{gs}	Gate Source Charge		-	3	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	3.5	-	nC

Switching Characteristics

t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 50V I _D = 5A, R _{GEN} = 3Ω	-	3.8	-	ns
t _r	Turn-On Rise Time		-	4.1	-	ns
t _{d(off)}	Turn-Off DelayTime		-	16	-	ns
t _f	Turn-Off Fall Time		-	8.5	-	ns

Drain-Source Diode Characteristics and Max Ratings

I _S	Maximum Continuous Drain to Source Diode Forward Current	V _{GS} = 0V, I _S = 20A	-	-	40	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	160	A
V _{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time		-	30	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	26	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting T_J=25°C, V_{DD}=50V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=16A
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Test Circuit



Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

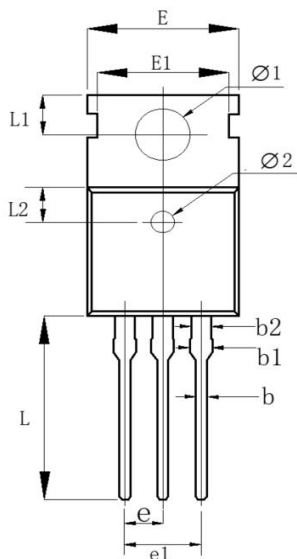


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform



Figure 4: Diode Recovery Test Circuit & Waveform

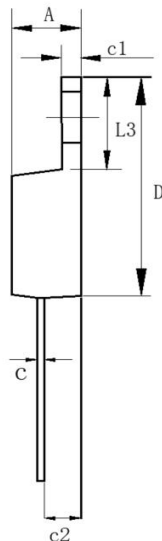
Package Mechanical Data(TO-220C-3L)



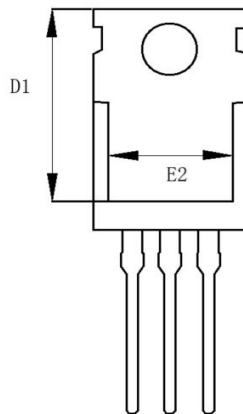
TOP VIEW



SIDE VIEW



SIDE VIEW



BOTTOM VIEW


COMMON DIMENSIONS (UNITS OF MEASURE=mm)			
SYMBOL	MIN	NOM	MAX
A	4.30	4.50	4.70
b	0.70	0.80	0.90
b1	—	—	1.42
b2	1.17	1.27	1.37
c	0.40	0.50	0.60
c1	1.25	1.30	1.35
c2	2.20	2.40	2.60
D	15.45	15.65	15.85
D1	13.20	13.40	13.60
E	9.80	10.00	10.20
E1	8.60	8.70	8.80
E2	7.80	8.00	8.20
e1	4.88	5.08	5.28
L	12.95	13.15	13.35
L1	2.70	2.80	2.90
L2	2.40	2.50	2.60
L3	6.30	6.50	6.70
Ø1	3.50	3.60	3.70
Ø2	1.35	1.50	1.65
e	2.54BSC		

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